

INTERNATIONAL STANDARD

NORME INTERNATIONALE



**Surface acoustic wave (SAW) and bulk acoustic wave (BAW) duplexers of assessed quality –
Part 1: Generic specification**

**Duplexeurs à ondes acoustiques de surface (OAS) et à ondes acoustiques de volume (OAV) sous assurance de la qualité –
Partie 1: Spécification générique**



THIS PUBLICATION IS COPYRIGHT PROTECTED

Copyright © 2015 IEC, Geneva, Switzerland

All rights reserved. Unless otherwise specified, no part of this publication may be reproduced or utilized in any form or by any means, electronic or mechanical, including photocopying and microfilm, without permission in writing from either IEC or IEC's member National Committee in the country of the requester. If you have any questions about IEC copyright or have an enquiry about obtaining additional rights to this publication, please contact the address below or your local IEC member National Committee for further information.

Droits de reproduction réservés. Sauf indication contraire, aucune partie de cette publication ne peut être reproduite ni utilisée sous quelque forme que ce soit et par aucun procédé, électronique ou mécanique, y compris la photocopie et les microfilms, sans l'accord écrit de l'IEC ou du Comité national de l'IEC du pays du demandeur. Si vous avez des questions sur le copyright de l'IEC ou si vous désirez obtenir des droits supplémentaires sur cette publication, utilisez les coordonnées ci-après ou contactez le Comité national de l'IEC de votre pays de résidence.

IEC Central Office
3, rue de Varembe
CH-1211 Geneva 20
Switzerland

Tel.: +41 22 919 02 11
Fax: +41 22 919 03 00
info@iec.ch
www.iec.ch

About the IEC

The International Electrotechnical Commission (IEC) is the leading global organization that prepares and publishes International Standards for all electrical, electronic and related technologies.

About IEC publications

The technical content of IEC publications is kept under constant review by the IEC. Please make sure that you have the latest edition, a corrigenda or an amendment might have been published.

IEC Catalogue - webstore.iec.ch/catalogue

The stand-alone application for consulting the entire bibliographical information on IEC International Standards, Technical Specifications, Technical Reports and other documents. Available for PC, Mac OS, Android Tablets and iPad.

IEC publications search - www.iec.ch/searchpub

The advanced search enables to find IEC publications by a variety of criteria (reference number, text, technical committee,...). It also gives information on projects, replaced and withdrawn publications.

IEC Just Published - webstore.iec.ch/justpublished

Stay up to date on all new IEC publications. Just Published details all new publications released. Available online and also once a month by email.

Electropedia - www.electropedia.org

The world's leading online dictionary of electronic and electrical terms containing more than 30 000 terms and definitions in English and French, with equivalent terms in 15 additional languages. Also known as the International Electrotechnical Vocabulary (IEV) online.

IEC Glossary - std.iec.ch/glossary

More than 60 000 electrotechnical terminology entries in English and French extracted from the Terms and Definitions clause of IEC publications issued since 2002. Some entries have been collected from earlier publications of IEC TC 37, 77, 86 and CISPR.

IEC Customer Service Centre - webstore.iec.ch/csc

If you wish to give us your feedback on this publication or need further assistance, please contact the Customer Service Centre: csc@iec.ch.

A propos de l'IEC

La Commission Electrotechnique Internationale (IEC) est la première organisation mondiale qui élabore et publie des Normes internationales pour tout ce qui a trait à l'électricité, à l'électronique et aux technologies apparentées.

A propos des publications IEC

Le contenu technique des publications IEC est constamment revu. Veuillez vous assurer que vous possédez l'édition la plus récente, un corrigendum ou amendement peut avoir été publié.

Catalogue IEC - webstore.iec.ch/catalogue

Application autonome pour consulter tous les renseignements bibliographiques sur les Normes internationales, Spécifications techniques, Rapports techniques et autres documents de l'IEC. Disponible pour PC, Mac OS, tablettes Android et iPad.

Recherche de publications IEC - www.iec.ch/searchpub

La recherche avancée permet de trouver des publications IEC en utilisant différents critères (numéro de référence, texte, comité d'études,...). Elle donne aussi des informations sur les projets et les publications remplacées ou retirées.

IEC Just Published - webstore.iec.ch/justpublished

Restez informé sur les nouvelles publications IEC. Just Published détaille les nouvelles publications parues. Disponible en ligne et aussi une fois par mois par email.

Electropedia - www.electropedia.org

Le premier dictionnaire en ligne de termes électroniques et électriques. Il contient plus de 30 000 termes et définitions en anglais et en français, ainsi que les termes équivalents dans 15 langues additionnelles. Egalement appelé Vocabulaire Electrotechnique International (IEV) en ligne.

Glossaire IEC - std.iec.ch/glossary

Plus de 60 000 entrées terminologiques électrotechniques, en anglais et en français, extraites des articles Termes et Définitions des publications IEC parues depuis 2002. Plus certaines entrées antérieures extraites des publications des CE 37, 77, 86 et CISPR de l'IEC.

Service Clients - webstore.iec.ch/csc

Si vous désirez nous donner des commentaires sur cette publication ou si vous avez des questions contactez-nous: csc@iec.ch.

INTERNATIONAL STANDARD

NORME INTERNATIONALE



**Surface acoustic wave (SAW) and bulk acoustic wave (BAW) duplexers of assessed quality –
Part 1: Generic specification**

**Duplexeurs à ondes acoustiques de surface (OAS) et à ondes acoustiques de volume (OAV) sous assurance de la qualité –
Partie 1: Spécification générique**

INTERNATIONAL
ELECTROTECHNICAL
COMMISSION

COMMISSION
ELECTROTECHNIQUE
INTERNATIONALE

ICS 31.140

ISBN 978-2-8322-2777-0

**Warning! Make sure that you obtained this publication from an authorized distributor.
Attention! Veuillez vous assurer que vous avez obtenu cette publication via un distributeur agréé.**

CONTENTS

FOREWORD.....	5
1 Scope.....	7
2 Normative references	7
3 Terms, definitions, units and symbols	8
3.1 Terms and definitions.....	8
3.1.1 General terms.....	9
3.1.2 Response characteristics related terms	10
3.1.3 SAW and BAW duplexers related terms	14
3.2 Units and graphical symbols	16
4 Order of precedence of documents.....	16
5 Preferred values for ratings and characteristics	16
5.1 General.....	16
5.2 Nominal frequency bands.....	16
5.3 Operating temperature ranges, in degrees Celsius (°C)	16
5.4 Climatic category	17
5.5 Bump severity	17
5.6 Vibration severity	17
5.7 Shock severity	18
5.8 Fine leak rate.....	18
6 Marking	18
6.1 Duplexer marking.....	18
6.2 Package marking.....	18
7 Quality assessment procedures.....	19
7.1 General.....	19
7.2 Primary stage of manufacture	19
7.3 Structurally similar components	19
7.4 Subcontracting.....	19
7.5 Incorporated components.....	19
7.6 Manufacturer's approval.....	19
7.7 Approval procedures.....	19
7.7.1 General	19
7.7.2 Capability approval	19
7.7.3 Qualification approval	20
7.8 Procedures for capability approval	20
7.8.1 General	20
7.8.2 Eligibility for capability approval.....	20
7.8.3 Application for capability approval	20
7.8.4 Granting of capability approval	20
7.8.5 Capability manual	20
7.9 Procedures for qualification approval	20
7.9.1 General	20
7.9.2 Eligibility for qualification approval.....	20
7.9.3 Application for qualification approval	21
7.9.4 Granting of qualification approval	21
7.9.5 Quality conformance inspection	21
7.10 Test procedures.....	21

7.11	Screening requirements	21
7.12	Rework and repair work	21
7.12.1	Rework	21
7.12.2	Repair work	21
7.13	Certified records of released lots	21
7.14	Validity of release	21
7.15	Release for delivery	21
7.16	Unchecked parameters	21
8	Test and measurement procedures	22
8.1	General	22
8.2	Test and measurement conditions	22
8.2.1	Standard conditions for testing	22
8.2.2	Precision of measurement	22
8.2.3	Precautions	22
8.2.4	Alternative test methods	23
8.3	Visual inspection	23
8.3.1	General	23
8.3.2	Visual test A	23
8.3.3	Visual test B	23
8.4	Dimensions test	23
8.5	Electrical test procedures	23
8.5.1	S parameters measurement	23
8.5.2	Intermodulation distortion measurement	25
8.5.3	Insulation resistance	25
8.5.4	Voltage proof	25
8.6	Mechanical and environmental test procedures	25
8.6.1	Sealing tests (non-destructive)	25
8.6.2	Soldering (solderability and resistance to soldering heat) (destructive)	26
8.6.3	Rapid change of temperature: severe shock by liquid immersion (non-destructive)	26
8.6.4	Rapid change of temperature with prescribed time of transition (non-destructive)	26
8.6.5	Bump (destructive)	26
8.6.6	Vibration (destructive)	27
8.6.7	Shock (destructive)	27
8.6.8	Free fall (destructive)	27
8.6.9	Acceleration, steady state (non-destructive)	28
8.6.10	Low air pressure (non-destructive)	28
8.6.11	Dry heat (non-destructive)	28
8.6.12	Damp heat, cyclic (destructive)	28
8.6.13	Cold (non-destructive)	28
8.6.14	Climatic sequence (destructive)	28
8.6.15	Damp heat, steady state (destructive)	29
8.6.16	Salt mist cyclic (destructive)	29
8.6.17	Immersion in cleaning solvents (non-destructive)	29
8.6.18	Flammability test (destructive)	29
8.6.19	Electrostatic discharge (ESD) sensitivity test (destructive)	29
8.7	Endurance test procedure	30
	Bibliography	31

Figure 1 – FBAR configuration 9
Figure 2 – SMR configuration..... 10
Figure 3 – Frequency response of SAW and BAW duplexers 15
Figure 4 – *S* parameters measurement..... 24

Table 1 – Frequency allocation of typical UMTS bands 16

iTeh STANDARD PREVIEW
(standards.iteh.ai)

[IEC 62604-1:2015](https://standards.iteh.ai/catalog/standards/sist/6e3bcd7-33d9-4671-8ab8-b903b2315a5e/iec-62604-1-2015)

<https://standards.iteh.ai/catalog/standards/sist/6e3bcd7-33d9-4671-8ab8-b903b2315a5e/iec-62604-1-2015>

INTERNATIONAL ELECTROTECHNICAL COMMISSION

**SURFACE ACOUSTIC WAVE (SAW) AND
BULK ACOUSTIC WAVE (BAW) DUPLEXERS
OF ASSESSED QUALITY –**

Part 1: Generic specification

FOREWORD

- 1) The International Electrotechnical Commission (IEC) is a worldwide organization for standardization comprising all national electrotechnical committees (IEC National Committees). The object of IEC is to promote international co-operation on all questions concerning standardization in the electrical and electronic fields. To this end and in addition to other activities, IEC publishes International Standards, Technical Specifications, Technical Reports, Publicly Available Specifications (PAS) and Guides (hereafter referred to as "IEC Publication(s)"). Their preparation is entrusted to technical committees; any IEC National Committee interested in the subject dealt with may participate in this preparatory work. International, governmental and non-governmental organizations liaising with the IEC also participate in this preparation. IEC collaborates closely with the International Organization for Standardization (ISO) in accordance with conditions determined by agreement between the two organizations.
- 2) The formal decisions or agreements of IEC on technical matters express, as nearly as possible, an international consensus of opinion on the relevant subjects since each technical committee has representation from all interested IEC National Committees.
- 3) IEC Publications have the form of recommendations for international use and are accepted by IEC National Committees in that sense. While all reasonable efforts are made to ensure that the technical content of IEC Publications is accurate, IEC cannot be held responsible for the way in which they are used or for any misinterpretation by any end user.
- 4) In order to promote international uniformity, IEC National Committees undertake to apply IEC Publications transparently to the maximum extent possible in their national and regional publications. Any divergence between any IEC Publication and the corresponding national or regional publication shall be clearly indicated in the latter.
- 5) IEC itself does not provide any attestation of conformity. Independent certification bodies provide conformity assessment services and, in some areas, access to IEC marks of conformity. IEC is not responsible for any services carried out by independent certification bodies.
- 6) All users should ensure that they have the latest edition of this publication.
- 7) No liability shall attach to IEC or its directors, employees, servants or agents including individual experts and members of its technical committees and IEC National Committees for any personal injury, property damage or other damage of any nature whatsoever, whether direct or indirect, or for costs (including legal fees) and expenses arising out of the publication, use of, or reliance upon, this IEC Publication or any other IEC Publications.
- 8) Attention is drawn to the Normative references cited in this publication. Use of the referenced publications is indispensable for the correct application of this publication.
- 9) Attention is drawn to the possibility that some of the elements of this IEC Publication may be the subject of patent rights. IEC shall not be held responsible for identifying any or all such patent rights.

International Standard IEC 62604-1 has been prepared by IEC technical committee 49: Piezoelectric, dielectric and electrostatic devices and associated materials for frequency control, selection and detection.

NOTE In this standard, SAW and BAW duplexers are treated simultaneously because both duplexers are used in the same manner especially in mobile phones and have the same requirements of characteristics, test method and so on.

The text of this standard is based on the following documents:

FDIS	Report on voting
49/1143/FDIS	49/1160/RVD

Full information on the voting for the approval of this standard can be found in the report on voting indicated in the above table.

This publication has been drafted in accordance with the ISO/IEC Directives, Part 2.

A list of all parts in the IEC 62604 series, published under the general title: *Surface acoustic wave (SAW) and bulk acoustic wave (BAW) duplexers of assessed quality*, can be found on the IEC website.

The committee has decided that the contents of this publication will remain unchanged until the stability date indicated on the IEC website under "<http://webstore.iec.ch>" in the data related to the specific publication. At this date, the publication will be

- reconfirmed,
- withdrawn,
- replaced by a revised edition, or
- amended.

IMPORTANT – The 'colour inside' logo on the cover page of this publication indicates that it contains colours which are considered to be useful for the correct understanding of its contents. Users should therefore print this document using a colour printer.

iTeh STANDARD PREVIEW (standards.iteh.ai)

[IEC 62604-1:2015](#)

<https://standards.iteh.ai/catalog/standards/sist/6e3bcd7-33d9-4671-8ab8-b903b2315a5e/iec-62604-1-2015>

SURFACE ACOUSTIC WAVE (SAW) AND BULK ACOUSTIC WAVE (BAW) DUPLEXERS OF ASSESSED QUALITY –

Part 1: Generic specification

1 Scope

This part of IEC 62604 specifies the methods of test and general requirements for SAW and BAW duplexers of assessed quality using either capability approval or qualification approval procedures.

2 Normative references

The following documents, in whole or in part, are normatively referenced in this document and are indispensable for its application. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

IEC 60027 (all parts), *Letter symbols to be used in electrical technology*

IEC 60050 (all parts), *International Electrotechnical Vocabulary* (available at www.electropedia.org)

IEC 60068-1:2013, *Environmental testing – Part 1: General and guidance*

IEC 60068-2-1, *Environmental testing – Part 2-1: Tests – Test A: Cold*

IEC 60068-2-2, *Environmental testing – Part 2-2: Tests – Test B: Dry heat*

IEC 60068-2-6, *Environmental testing – Part 2-6: Tests – Test Fc: Vibration (sinusoidal)*

IEC 60068-2-7, *Basic environmental testing procedures – Part 2-7: Tests – Test Ga and guidance: Acceleration, steady state*

IEC 60068-2-13, *Basic environmental testing procedures – Part 2-13: Tests – Test M: Low air pressure*

IEC 60068-2-14, *Environmental testing – Part 2-14: Tests – Test N: Change of temperature*

IEC 60068-2-17:1994, *Basic environmental testing procedures – Part 2-17: Tests – Test Q: Sealing*

IEC 60068-2-27, *Environmental testing – Part 2-27: Tests – Test Ea and guidance: Shock*

IEC 60068-2-30, *Environmental testing – Part 2-30: Tests – Test Db: Damp heat, cyclic (12 h + 12 h cycle)*

IEC 60068-2-31, *Environmental testing – Part 2-31: Tests – Test Ec: Rough handling shocks, primarily for equipment-type specimens*

IEC 60068-2-45, *Basic environmental testing procedures – Part 2-45: Tests – Test XA and guidance: Immersion in cleaning solvents*

IEC 60068-2-52, *Environmental testing – Part 2-52: Tests – Test Kb: Salt mist, cyclic (sodium chloride solution)*

IEC 60068-2-58, *Environmental testing – Part 2-58: Tests – Test Td: Test methods for solderability, resistance to dissolution of metallization and to soldering heat of surface mounting devices (SMD)*

IEC 60068-2-64, *Environmental testing – Part 2-64: Tests – Test Fh: Vibration, broad-band random and guidance*

IEC 60068-2-78, *Environmental testing – Part 2-78: Tests – Test Cab: Damp heat, steady state*

IEC 60122-1, *Quartz crystal units of assessed quality – Part 1: Generic specification*

IEC 60617, *Graphical symbols for diagrams* (available at <http://std.iec.ch/iec60617>)

IEC 60642, *Piezoelectric ceramic resonators and resonator units for frequency control and selection – Chapter I: Standard values and conditions – Chapter II: Measuring and test conditions*

iTeh STANDARD PREVIEW

IEC 60695-11-5, *Fire hazard testing – Part 11-5: Test flames – Needle-flame test method – Apparatus, confirmatory test arrangement and guidance*

IEC 60749-28¹, *Semiconductor devices – mechanical and climatic test methods – Part 28: Electrostatic Discharge (ESD) Sensitivity testing direct contact charged device model (DC-CDM)*

IEC 61000-4-2, *Electromagnetic compatibility (EMC) – Part 4-2: Testing and measurement techniques – Electrostatic discharge immunity test*

IEC 61340-3-1, *Electrostatics – Part 3-1: Methods for simulation of electrostatic effects – Human body model (HBM) electrostatic discharge test waveforms*

IEC 61340-3-2, *Electrostatics – Part 3-2: Methods for simulation of electrostatic effects – Machine model (MM) electrostatic discharge test waveforms*

IEC 62761, *Guidelines for the measurement method of nonlinearity for surface acoustic wave (SAW) and bulk acoustic wave (BAW) devices in radio frequency (RF)*

IEC 80000 (all parts), *Quantities and units*

ISO 80000 (all parts), *Quantities and units*

3 Terms, definitions, units and symbols

3.1 Terms and definitions

For the purposes of this document, the following terms and definitions apply.

¹ To be published.

3.1.1 General terms

3.1.1.1

surface acoustic wave

SAW

acoustic wave, propagating along a surface of an elastic material, whose amplitude decays exponentially with the depth

[SOURCE: IEC 60862-1:2003, 2.2.1.1, modified — In the definition, "elastic substrate" has been replaced with "elastic material" and "substrate depth" has been replaced with "the depth".]

3.1.1.2

surface acoustic wave filter

SAW filter

filter characterized by one or more surface acoustic wave transmission line or resonant elements, where the surface acoustic wave is usually generated by an interdigital transducer and propagates along a material surface

[SOURCE: IEC 60862-1:2003, 2.2.1.2, modified]

3.1.1.3

bulk acoustic wave

BAW

acoustic wave, propagating inside an elastic material and then traversing the entire thickness of the bulk

3.1.1.4

bulk acoustic wave filter

BAW filter

filter characterized by a bulk acoustic wave which is usually generated by a pair of electrodes and propagates along a thickness direction

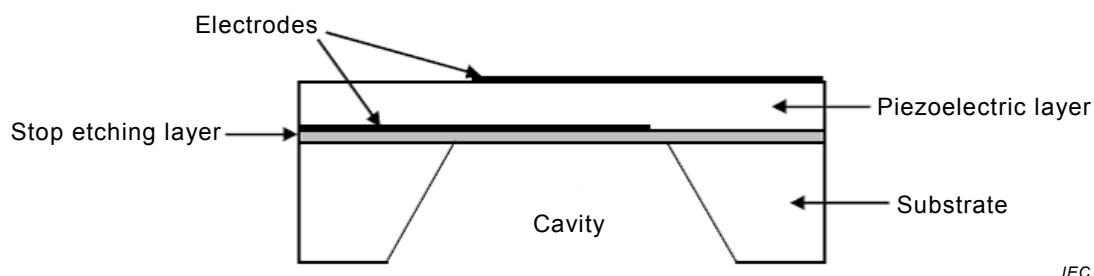
3.1.1.5

film bulk acoustic resonator

FBAR

thin film BAW resonator consisting of a piezoelectric layer sandwiched between two electrode layers with stress-free top and bottom surface supported mechanically at the edge on a substrate with cavity structure as shown in Figure 1 or membrane structure as an example

Note 1 to entry: This note applies to the French language only.



IEC

Figure 1 – FBAR configuration

3.1.1.6

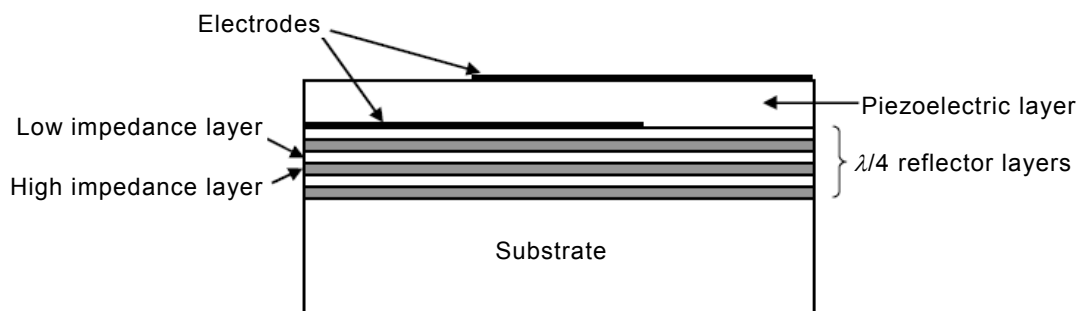
solidly mounted resonator

SMR

BAW resonator, supporting the electrode/piezoelectric layer/electrode structure by a sequence of additional thin films of alternately low and high acoustic impedance with quarter

wavelength layer, these layers acting as acoustic reflectors and decoupling the resonator acoustically from the substrate, as shown in Figure 2 as an example

Note 1 to entry: This note applies to the French language only.



IEC

Figure 2 – SMR configuration

3.1.2 Response characteristics related terms

3.1.2.1

reference frequency

frequency defined by the specification to which other frequencies may be referred

[SOURCE: IEC 60862-1:2003, 2.2.2.3]

iTech STANDARD PREVIEW
(standards.iteh.ai)

3.1.2.2

insertion attenuation

logarithmic ratio of the power delivered directly to the load impedance before insertion of the duplexer to the power delivered to the load impedance after insertion of the duplexer

[SOURCE: IEC 60862-1:2003, 2.2.2.6, modified — In the definition, "filter" has been replaced with "duplexer".]

3.1.2.3

nominal insertion attenuation

insertion attenuation at a specified reference frequency

[SOURCE: IEC 60862-1:2003, 2.2.2.7]

3.1.2.4

relative attenuation

difference between the attenuation at a given frequency and the attenuation at the reference frequency

[SOURCE: IEC 60862-1:2003, 2.2.2.8]

3.1.2.5

pass band

band of frequencies in which the relative attenuation is equal to or less than a specified value

[SOURCE: IEC 60862-1:2003, 2.2.2.9]

3.1.2.6

pass bandwidth

separation of frequencies between which the relative attenuation is equal to or less than a specified value

[SOURCE: IEC 60862-1:2003, 2.2.2.10]

3.1.2.7

pass band ripple

maximum variation in attenuation characteristics within a specified pass band

[SOURCE: IEC 60862-1:2003, 2.2.2.11]

3.1.2.8

minimum insertion attenuation

minimum value of insertion attenuation in the pass band

[SOURCE: IEC 60862-1:2003, 2.2.2.13]

3.1.2.9

maximum insertion attenuation

maximum value of insertion attenuation in the pass band

[SOURCE: IEC 60862-1:2003, 2.2.2.14]

3.1.2.10

stop band

band of frequencies in which the relative attenuation is equal to or greater than a specified value

[SOURCE: IEC 60862-1:2003, 2.2.2.15]

3.1.2.11

stop bandwidth

separation of frequencies between which the relative attenuation is equal to or greater than a specified value

[SOURCE: IEC 60862-1:2003, 2.2.2.16]

3.1.2.12

stop band rejection

minimum relative attenuation at a specified stop band

3.1.2.13

group delay

time equal to the first derivative of the phase shift, in radians, with respect to the angular frequency

[SOURCE: IEC 60862-1:2003, 2.2.2.18]

3.1.2.14

trap frequency

specified frequency at which the relative attenuation is equal to or greater than a specified value

[SOURCE: IEC 60862-1:2003, 2.2.2.21]

3.1.2.15

trap attenuation

relative attenuation at a specified trap frequency

[SOURCE: IEC 60862-1:2003, 2.2.2.22]

3.1.2.16
transition band

band of frequencies between the cut-off frequency and the nearest point of the adjacent stop band

[SOURCE: IEC 60862-1:2003, 2.2.2.23]

3.1.2.17
reflectivity

dimensionless measure of the degree of mismatch between two impedances Z_a and Z_b :

$$\frac{Z_a - Z_b}{Z_a + Z_b},$$

where Z_a and Z_b represent, respectively, the input and source impedance or the output and load impedance

Note 1 to entry: The absolute value of reflectivity is called the reflection coefficient.

3.1.2.18
return attenuation

value of the reflection coefficient given by the sign changed expression in decibels:

$$-20 \log \left| \frac{Z_a - Z_b}{Z_a + Z_b} \right| \text{ dB}$$

IEC 62604-1:2015

[SOURCE: IEC 60862-1:2003, 2.2.2.25, modified]

3.1.2.19
input level

power, voltage or current value applied to the input port of a duplexer

[SOURCE: IEC 60862-1:2003, 2.2.2.29, modified — In the definition, "input terminal pair of a filter" has been replaced with "input port of a duplexer".]

3.1.2.20
output level

power, voltage or current value delivered to the load circuit

[SOURCE: IEC 60862-1:2003, 2.2.2.30, modified — In the definition, "load" has been replaced with "load circuit".]

3.1.2.21
nominal level

power, voltage or current value at which the performance measurement is specified

[SOURCE: IEC 60862-1:2003, 2.2.2.31]

3.1.2.22
input impedance

impedance presented by the duplexer to the signal source when the output is terminated by a specified load impedance

[SOURCE: IEC 60862-1:2003, 2.2.2.32, modified — In the definition, "filter" has been replaced with "duplexer".]

3.1.2.23

output impedance

impedance presented by the duplexer to the load when the input is terminated by a specified source impedance

[SOURCE: IEC 60862-1:2003, 2.2.2.33, modified — In the definition, "filter" has been replaced with "duplexer".]

3.1.2.24

terminating impedance

impedance presented to the duplexer by the source or by the load

[SOURCE: IEC 60862-1:2015, 3.1.2.35, modified — In the definition, "filter" has been replaced with "duplexer".]

3.1.2.25

operating temperature range

range of temperatures, over which the SAW or BAW duplexer will function while maintaining its specified characteristics within specified tolerances

[SOURCE: IEC 60862-1:2003, 2.2.2.37, modified — In the definition, "SAW filter" has been replaced with "SAW or BAW duplexer".]

3.1.2.26

intermodulation distortion

IMD

non-linear distortion of a device response characterized by the appearance of frequencies at the output which is equal to the differences (or sums) of integral multiples of the two or more component frequencies present at the input

[SOURCE: IEC 60862-1:2003, 2.2.2.41, modified — The abbreviation "IMD" has been added. In the definition, "SAW transducer or filter" has been replaced with "device".]

Note 1 to entry: This note applies to the French language only.

3.1.2.27

duplex image frequency

f_{DIM}

undesired input frequency that is converted to the receiving frequency (f_R) by subtracting it from twice the transmitting frequency ($2f_T$)

$$f_{DIM} = 2f_T - f_R$$

3.1.2.28

isolation

isolation from TX port to RX port

leakage power ratio from the TX port to the RX port in a duplexer

Note 1 to entry: Figure 3c gives an example of isolation response.

3.1.2.29

guard band

unused part of the radio spectrum between radio bands, for the purpose of preventing interference